



Product End-of-Life Disassembly Instructions

Product Type/ Category: Notebook

Product Name / Model: APD Nomada

1. **Purpose:** This document is intended for use by End-Of-Life (EOL) recyclers, reusers or treatment facilities. It provides the basic instructions for the disassembly of products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EU, Waste Electrical and Electronic Equipment (WEEE).
2. **Compliance:** EU directive 2012/19/EU WEEE - Annex VII materials.

| EU directive 2012/19/EU WEEE - Annex VII materials | | |
|--|---|----------|
| Contain (Yes/No) | Component | Quantity |
| Polychlorinated biphenyls (PCB) containing capacitors in accordance with Council Directive 96/59/EC of 16 September 1996 on the disposal of polychlorinated biphenyls and polychlorinated terphenyls (PCB/PCT) | | |
| No | | |
| Mercury containing components, such as switches or backlighting lamps | | |
| No | | |
| Batteries | | |
| Yes | Battery Button Cell | 2 |
| Printed circuit boards of mobile phones generally, and of other devices if the surface of the printed circuit board is greater than 10 square centimeters | | |
| Yes | Main Printed Circuit Board I/O Printed Circuit Board | 2 |
| Toner cartridges, liquid and paste, as well as colour toner | | |
| No | | |
| Plastic containing brominated flame retardants | | |
| No | | |
| Asbestos waste and components which contain asbestos | | |
| No | | |
| Cathode ray tubes | | |
| No | | |
| Chlorofluorocarbons (CFC), hydrochlorofluorocarbons (HCFC) or hydrofluorocarbons (HFC), hydrocarbons (HC) | | |
| No | | |

| | | |
|---|------------------------------|---|
| Gas discharge lamps | | |
| No | | |
| Liquid crystal displays (together with their casing where appropriate) of a surface greater than 100 square centimetres and all those back-lighted with gas discharge lamps | | |
| Yes | Liquid Crystal Display (LCD) | 1 |
| External electric cables | | |
| Yes | Power Cords Adapter | 2 |
| Components containing refractory ceramic fibres as described in Commission Directive 97/69/EC of 5 December 1997 adapting to technical progress for the 23rd time Council Directive 67/548/EEC on the approximation of the laws, regulations and administrative provisions relating to the classification, packaging and labelling of dangerous substances | | |
| No | | |
| Components containing radioactive substances with the exception of components that are below the exemption thresholds set in Article 3 of and Annex I to Council Directive 96/29/Euratom of 13 May 1996 laying down basic safety standards for the protection of the health of workers and the general public against the dangers arising from ionizing radiation | | |
| No | | |
| Electrolyte capacitors containing substances of concern (height > 25 mm, diameter > 25 mm or proportionately similar volume) | | |
| No | | |

3. **Tools required:** List of the tools that would usually be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

| Tool Description | Type/size | Quantity |
|------------------|-----------|----------|
| Screwdriver | PH0 | 1 |

4. **Product Disassembly Process:** List of the steps that should usually be followed to remove components and materials requiring selective treatment.

| Step | Activity | Description |
|------|--------------------|---|
| 1 | Remove Bottom Case | Remove all screws (x11) / Remove the bottom case |
| 2 | Remove Battery | Remove all screws (x6) / Remove the power connector |
| 3 | Remove SSD | Remove the screw (x1) / Remove the SSD |
| 4 | Remove RAM | Remove the stickers / Remove RAM |
| 5 | Remove Fan | Remove the sticker / Remove all screws (x7) / Remove fan connector |
| 6 | Remove WiFi module | Remove the screw (x1) / Remove WiFi connectors |
| 7 | Remove Bottom Cell | Remove bottom cell connector / Remove bottom cell |
| 8 | Remove Speaker | Remove speaker connector / Remove speakers (x2) |
| 9 | Remove Main PCB | Remove all screws (x7) / Remove LCD connector / Remove data connectors (x6) / Remove main PCB |

| | | |
|----|--------------------|--|
| 10 | Remove I/O PCB | Remove all screws (x4) / Remove data connectors (x4) / Remove I/O PCB |
| 11 | Remove Touch Panel | Remove all screws (x2) / Remove data connectors (x2) / Remove touch panel |
| 12 | Remove LCD | Remove all hinge-PCB screws (x3) / Remove LCD bezel / Remove all LCD screws (x4) / Remove LCD / Remove all hinge-LCD screws (x6) / Remove webcam |

5. **Product Disassembly Graphic Process:** If the disassembly process is complex, follow the illustrations below to identify the components contained in the product that require selective treatment.

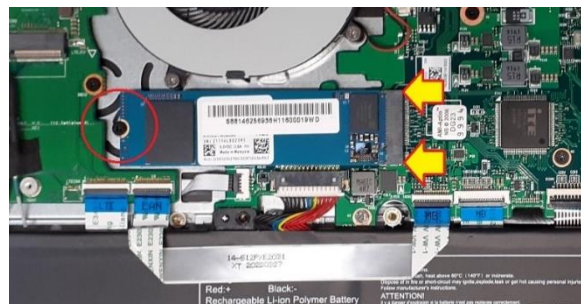
Step 1. Remove Bottom Case



Step 2. Remove Battery (Li-Ion)



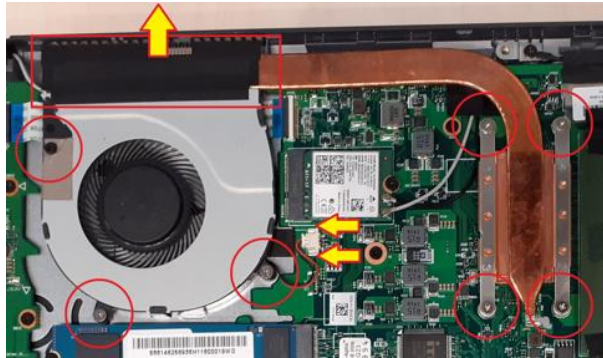
Step 3. Remove SSD



Step 4. Remove RAM



Step 5. Remove Fan



Step 6. Remove WiFi module



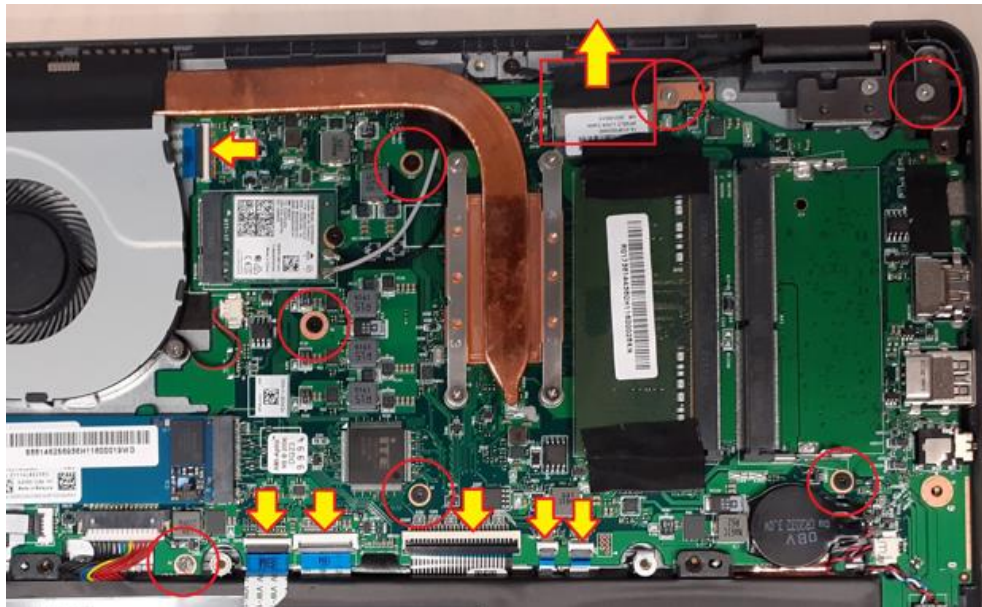
Step 7. Remove Bottom Cell (Li-Ion)



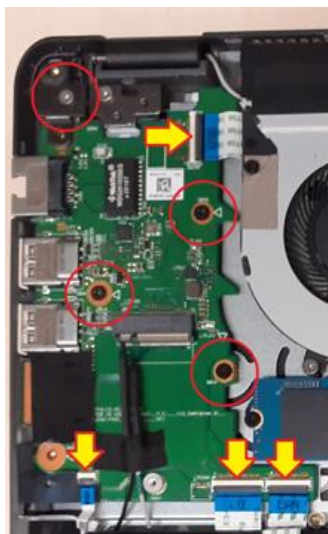
Step 8. Remove Speaker



Step 9. Remove Main PCB



Step 10. Remove I/O PCB



Step 11. Remove Touch Panel



Step 12. Remove LCD

